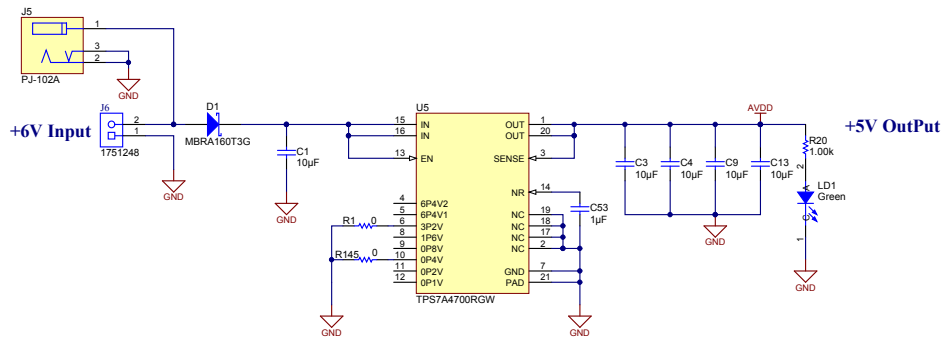
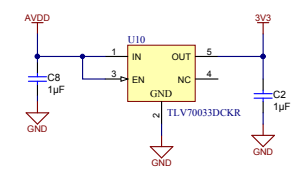


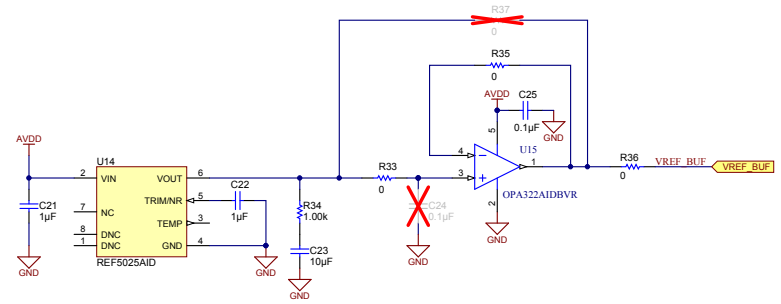
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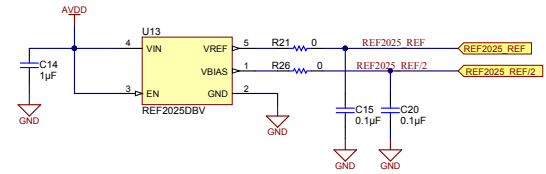
+6V to +5V Conversion



+5V to +3.3V Conversion

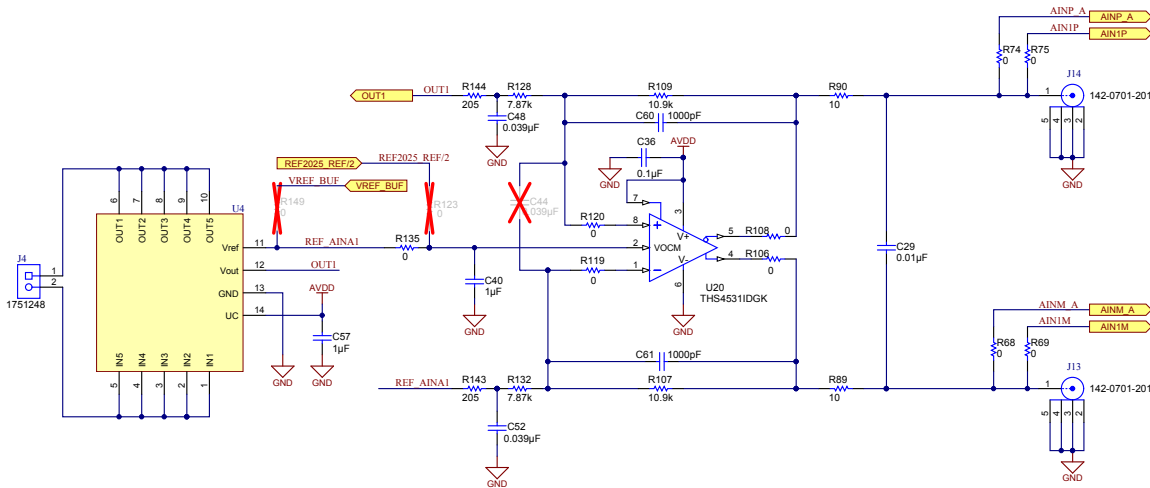


+2.5V Reference

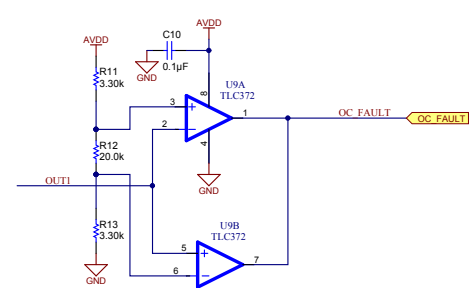


+2.5V Reference and +1.25V Bias supply

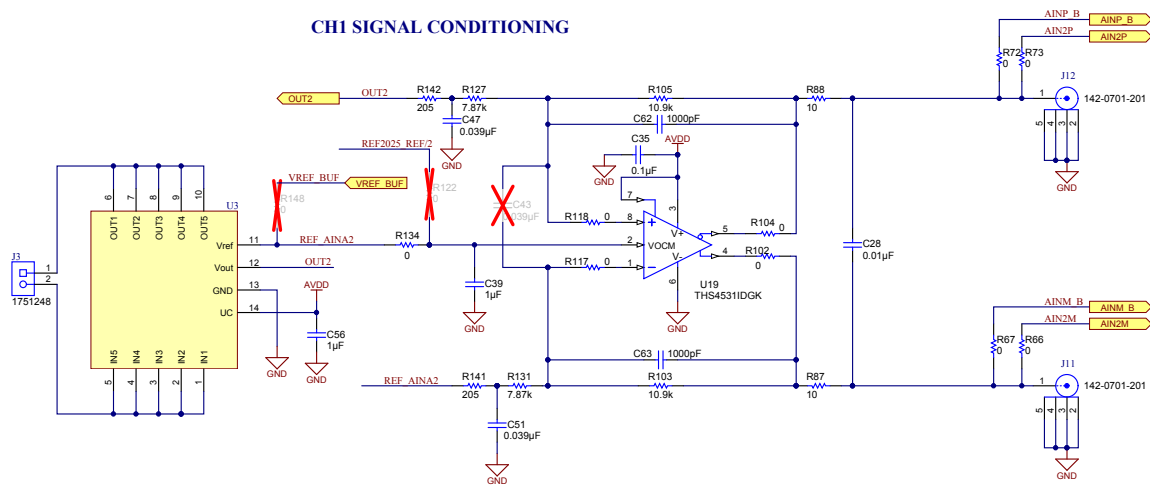
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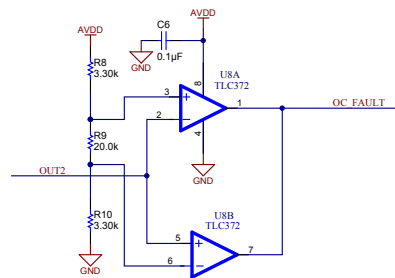
CH1 SIGNAL CONDITIONING



CH1 OVERCURRENT FAULT DETECTION



CH2 SIGNAL CONDITIONING

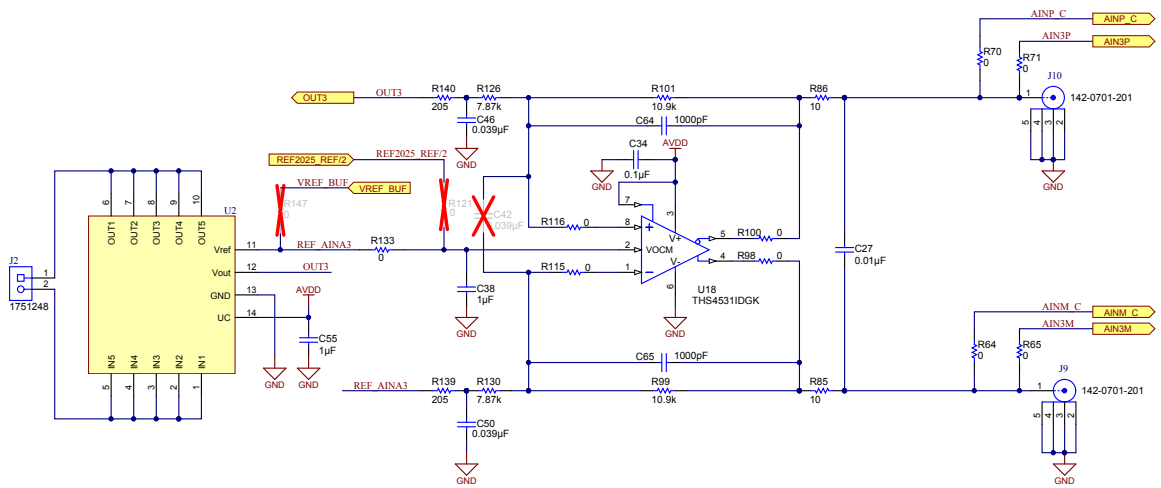


CH2 OVERCURRENT FAULT DETECTION

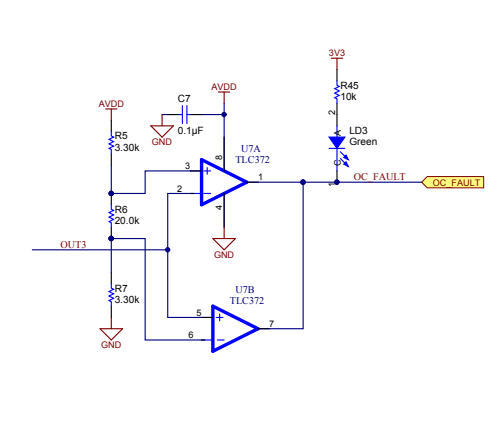
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Number: TIDA-00201	Rev: E2	Designed for: Public Release	Mod Date: 9/29/2014
SVN Rev: Not in version control		Project Title: DE I/P ADC Signal Conditioning For Fluxgate Senses	
Drawn By: Sanjay Pithadia		Sheet Title: Main	Assembly Variant: 001
Engineer: Sanjay Pithadia	Contact: http://www.ti.com/support	File: Pkg_Channel-1_2_SchDoc	Sheet 3 of 7
		Size: B	http://www.ti.com

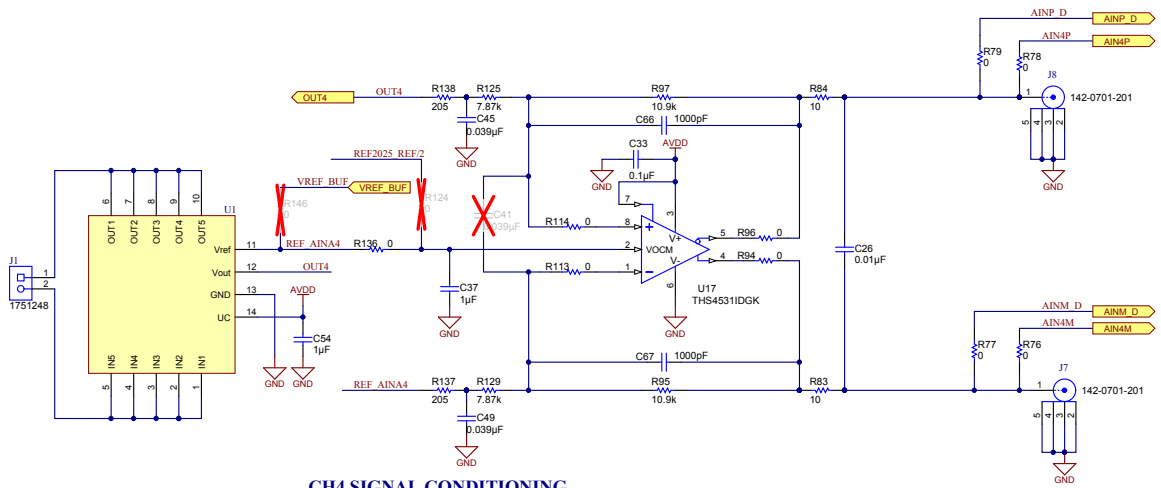




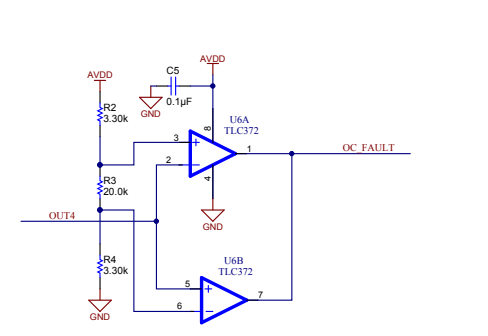
CH3 SIGNAL CONDITIONING



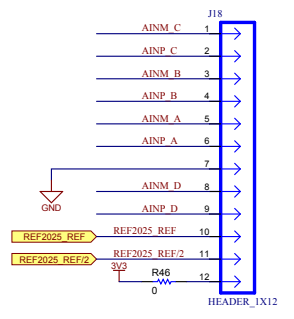
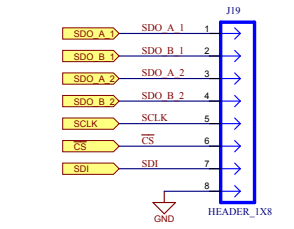
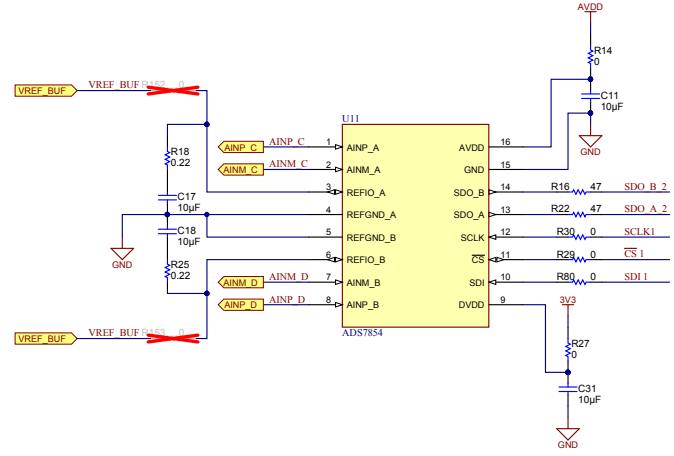
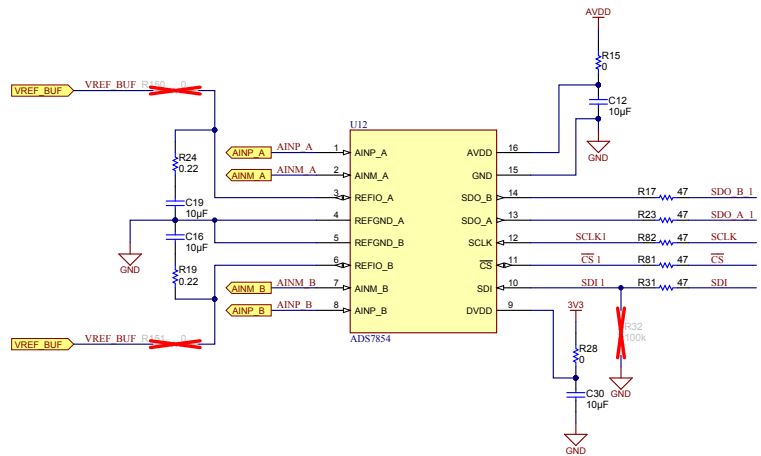
CH3 OVERCURRENT FAULT DETECTION



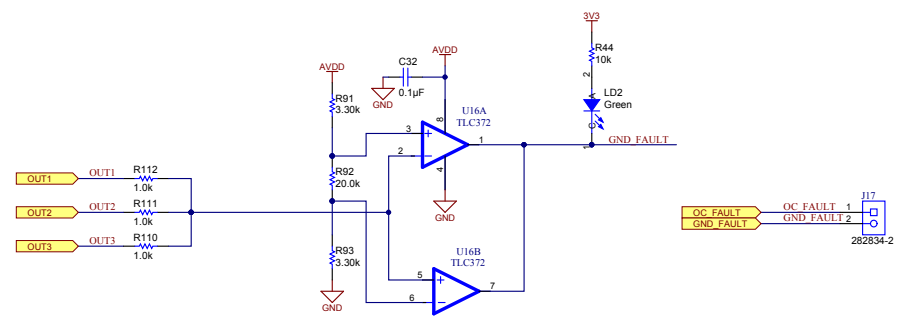
CH4 SIGNAL CONDITIONING



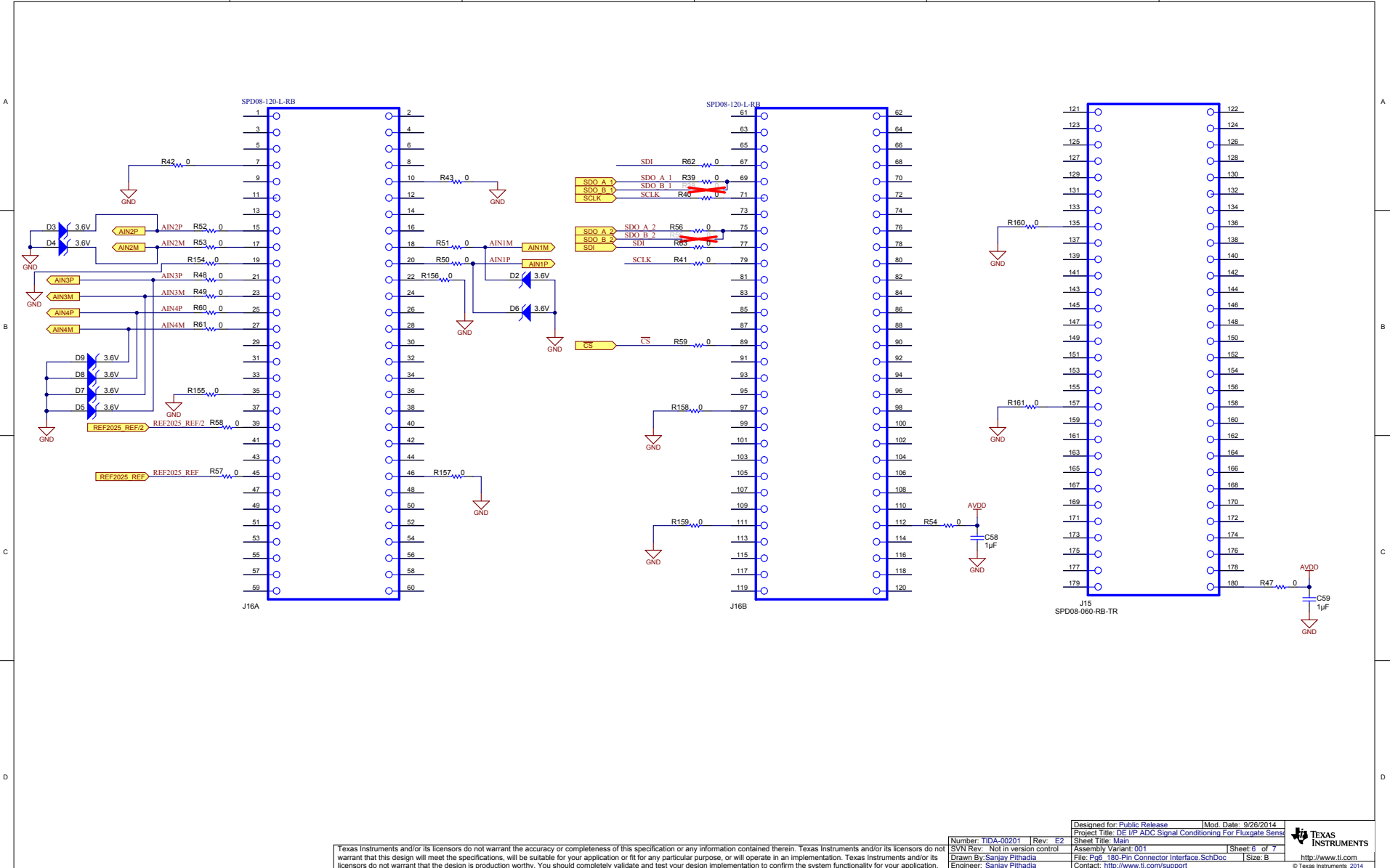
CH4 OVERCURRENT FAULT DETECTION



TWO ADS7854s FOR INTERFACING WITH EXTERNAL MOTOR CONTROLLER



GROUND FAULT DETECTION



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Number: TIDA-00201	Rev: E2	Mod Date: 9/26/2014	Decided for: Public Release
SVN Rev: Not in version control		Project Title: DE I/P ADC Signal Conditioning For Fluxgate SENS	Sheet Title: Main
Drawn By: Sanjay Pithadia		File: Pkg_160-Pin Connector Interface.SchDoc	Sheet 6 of 7
Engineer: Sanjay Pithadia		Contact: http://www.ti.com/support	Size: B

<http://www.ti.com>

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1 2 3 4 5 6

A

H2 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH H1 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH

H7 1902C H6 1902C H8 1902C H5 1902C

FID2 FID1 FID3 FID6 FID5 FID4

PCB Number: TIDA-00201
PCB Rev: E2

PCB LOGO
Texas Instruments

B

A

B

C

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

C

D

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Designed for: Public Release		Mod. Date: 10/17/2014	
Project Title: DE I/P ADC Signal Conditioning For Fluxgate Senses			
Number: TIDA-00201	Rev: E2	Sheet Title:	
SVN Rev.: Not in version control		Assembly Variant: 001	Sheet: 7 of 7
Drawn By:	Engineer: Sanjay Pithadia	File: P27_Hardware_ANSI-B_SchDoc	Size: B
		Contact: http://www.ti.com/support	http://www.ti.com
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1 2 3 4 5 6

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